

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1910-01		DATE: 29-Oct-2019	MEANS OF DISTINGUISHING CHANGED DEVICES:	
Product Affected: FCCSP-53, FCCSP-253 (Refer to attachment II for affected part#)			☐ Product Mark	Traceable through lot#
			☒ Back Mark	
			☐ Date Code	
			☐ Other	
Date Effective: 29-Jan-2020				
Contact: PCN DESK	Attachment:		☒ Yes	☐ No
E-mail: idt-pcn@lm.renesas.com	Samples: N/A			

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☒ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

This notification is to advise our customers that Sample Open/Short test will be introduced at Assembly Process at Amkor Korea and Stats Chippac, Korea at the request of the customers.

Attachment I details the process flow.
Attachment II lists the affected part numbers.

RELIABILITY/QUALIFICATION SUMMARY:

N/A

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ Approval for shipments prior to effective date.
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

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ATTACHMENT I - PCN # : A1910-01

PCN Type: Assembly Process

Data Sheet Change: None

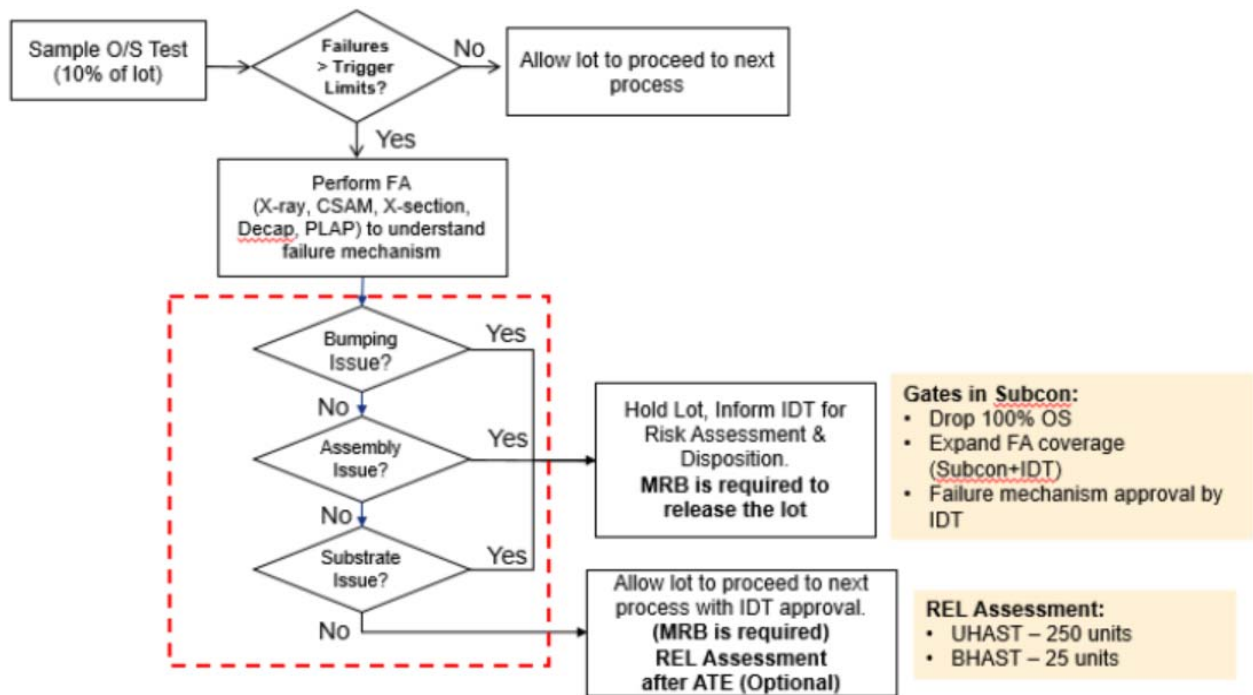
No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that Sample Open/Short test will be introduced at Assembly Process at Amkor Korea and Stats Chippac, Korea at the request of the customers.

Assembly process flow as detailed below.

Assembly Sample Open/Short Test and 3-sigma Trigger Limit Disposition Flow



Bumping Issue: Missing bumps, Open bumps, UBM Defects, RDL defects.

Assembly Issue: Bump bridge, Missing bump, Delamination, Die Crack.

Substrate Issue: Shorting Trace, Open Trace, Open Via.

PRODUCT/PROCESS CHANGE NOTICE (PCN)**ATTACHMENT II - PCN # : A1910-01****Affected Part Numbers**

Part Number	Part Number	Part Number	Part Number
4DB0226EMKB0AVG	4DB0226KB0AVG8	4RCD0124KC0ATGI	4RCD0232EMKC1ATG8
4DB0226EMKB0AVG8	4DB0232KC2AVG	4RCD0124KC0ATGI8	4RCD0232KC1ATG
4DB0226KA3AVG	4DB0232KC2AVG8	4RCD0229KB1ATG	4RCD0232KC1ATG8
4DB0226KA3AVG8	4RCD0124KC0ATG	4RCD0229KB1ATG8	X026LP1AVG
4DB0226KB0AVG	4RCD0124KC0ATG8	4RCD0232EMKC1ATG	X026LP1AVG8